



CALL FOR INVITED PAPERS

IEEE CARL K. CHANG SYMPOSIUM ON SOFTWARE SERVICES ENGINEERING at IEEE SERVICES 2023

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**JULY 2-3
2023**

**CHICAGO,
ILLINOIS
USA**

Hybrid Event

The IEEE Carl K. Chang Symposium on Software Services Engineering (SSE) will be held on July 2-3, 2023 as a special event at the 2023 IEEE World Congress on Services (SERVICES). The symposium will serve a double function, celebrating the career of Carl K. Chang, a visionary in software engineering and services computing, and featuring some of the leading voices in research and industry supporting the integration of these two critical areas for advancing the future of computing across the globe.

Please join Carl, his colleagues, collaborators, students, mentors and friends as we honor his accomplishments, commemorate his successes, and envision the future of software engineering, requirements engineering, and services computing at the symposium celebrating his outstanding 4+ decades of research, teaching, and service in computing.



Important Dates for Invited Symposium Papers:

January 1, 2023: EasyChair opens for draft submissions

UPDATED: April 26, 2023: EasyChair closes for submissions

UPDATED: May 15, 2023: Acceptance notifications

July 2-3, 2023: IEEE CKC Symposium on SSE at IEEE SERVICES



Contact: For any questions regarding submission of invited papers, please email Dr. Sheikh Iqbal Ahamed at sheikh.ahamed@marquette.edu



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